

Special Issue

Latest Advances and Applications of Food Packaging Materials

Message from the Guest Editors

As a consequence of the growth in the population and the improving quality of life, food demand will double by 2050. One way to meet this requirement is to reduce food losses from the supply chain. In this context, new food packaging materials that have good barrier properties against water vapors and gases will play a key role in meeting the growing food demands. On the other hand, non-biodegradable plastics that are commonly used for food packaging have created daunting challenges such as over-burdened landfills and the proliferation of ocean microplastics. This Special issue aims to cover the latest advances and applications of food packaging materials. We highly welcome articles describing scientific or engineering advancements in the field of food packaging materials.

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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